LINEAR TECHNOLOGY MATERIALS DECLARATION

LTC6652BHMS8-2.5#TRPBF **(Engineering Calculation)** MSOP

TOTAL MASS (g): **0.02714403**

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COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.
Active Device	Linear Technology	Silicon (Si)	7440-21-3	**0.001907**	**1000000**	**70254.87**
Die Coat	Dow Corning	Silicone	67762-90-7	**0**	**0**	**0**
Lead Frame	Cu	Copper (Cu)	7440-50-8	0	0	0
		Iron (Fe)	7439-89-6	0.006206	580000	228632.3
		Phosporus (P)	7723-14-0	0	0	0
		Zinc (Zn)	7440-66-6	0	0	0
		Nickel (Ni)	7440-02-0	0.004494	420000	165561.3
		Silicon (Si)	7440-21-3	0	0	0
		Magnesium (Mg)	7439-95-4	0	0	0
		Tin (Sn)	7440-31-5	0	0	0
		Lead Frame Total:		**0.0107**	**1000000**	**394193.6**
Plating	PMI	Exter. Plating Pb	7439-92-1	0	0	0
		Exter. Plating Sn	7440-31-5	0.000710025	1000000	26157.69
		External Plating Total:		**0.000710025**	**1000000**	**26157.69**
		Inter. Plating Ni	7440-02-0	0	0	0
		Inter. Plating Ag	7440-22-4	8.6E-05	1000000	3168.285
		Internal Plating Total:		**8.6E-05**	**1000000**	**3168.285**
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000668	750000	24609.47
		Tin (Sn)	7440-31-5	0	0	0
		Lead (Pb)	7439-92-1	0	0	0
		Silica (SiO2)	60676-86-0	0	0	0
		Metal Oxide		0	0	0
		Resin (EP)		0.000223	250000	8215.436
		Die Attach Total:		**0.000891**	**1000000**	**32824.9**
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.001659	130000	61118.42
		Bromine (Br)	40039-93-8	0	0	0
		Silica (SiO2)	60676-86-0	0.010591	830000	390177.9
		Antimony Trioxide (Sb2O3)	1309-64-4	0	0	0
		Metal Hydroxid		0.000447	35000	16467.71
		Carbon Black (C)	1333-86-4	6.4E-05	5000	2357.793
		Encapsulation Total:		**0.012761**	**1000000**	**470121.9**
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	**8.9E-05**	**1000000**	**3278.806**

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